

## IGBT Chip in NPT-technology

### FEATURES:

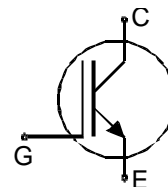
- 1200V NPT technology 180µm chip
- low turn-off losses
- short tail current
- positive temperature coefficient
- easy paralleling

### This chip is used for:

- power module  
BSM25GD120DLC E3224

### Applications:

- drives



| Chip Type    | V <sub>CE</sub> | I <sub>Cn</sub> | Die Size                    | Package      | Ordering Code     |
|--------------|-----------------|-----------------|-----------------------------|--------------|-------------------|
| SIGC42T120CL | 1200V           | 25A             | 6.59 x 6.49 mm <sup>2</sup> | sawn on foil | C67078-A4675-A001 |
| SIGC42T120CL | 1200V           | 25A             | 6.59 x 6.49 mm <sup>2</sup> | unsawn       | C67078-A4675-A002 |

### MECHANICAL PARAMETER:

|                                 |  |                 |
|---------------------------------|--|-----------------|
| Raster size                     | 6.59 x 6.49  | mm <sup>2</sup> |
| Emitter pad size                | 2 x ( 2.18 x 1.58 )  |                 |
| Gate pad size                   | 1.06 x 0.65  |                 |
| Area total / active             | 42.8 / 33.5  |                 |
| Thickness                       | 180  | µm              |
| Wafer size                      | 150  | mm              |
| Flat position                   | 90   | grd             |
| Max.possible chips per wafer    | 334 pcs  |                 |
| Passivation frontside           | Photoimide   |                 |
| Emitter metallization           | 3200 nm Al Si 1%   |                 |
| Collector metallization         | 1400 nm Ni Ag –system<br>suitable for epoxy and soft solder die bonding                      |                 |
| Die bond                        | electrically conductive glue or solder   |                 |
| Wire bond                       | Al, <500µm   |                 |
| Reject Ink Dot Size             | Ø 0.65mm ; max 1.2mm   |                 |
| Recommended Storage Environment | store in original container, in dry nitrogen,<br>< 6 month at an ambient temperature of 23°C |                 |

## MAXIMUM RATINGS:

| Parameter   | Symbol         | Value         | Unit               |
|---|----------------|---------------|--------------------|
| Collector-emitter voltage, $T_j=25\text{ °C}$         | $V_{CE}$       | 1200          | V                  |
| DC collector current, limited by $T_{jmax}$           | $I_C$          | <sup>1)</sup> | A                  |
| Pulsed collector current, $t_p$ limited by $T_{jmax}$ | $I_{Cpuls}$    | 75            | A                  |
| Gate emitter voltage                                  | $V_{GE}$       | $\pm 20$      | V                  |
| Operating junction and storage temperature            | $T_j, T_{stg}$ | -55 ... +150  | $^{\circ}\text{C}$ |

<sup>1)</sup> depending on thermal properties of assembly

## STATIC CHARACTERISTICS (tested on chip), $T_j=25\text{ °C}$ , unless otherwise specified:

| Parameter                            | Symbol        | Conditions                | Value |      |      | Unit          |
|--------------------------------------|---------------|---------------------------|-------|------|------|---------------|
|                                      |               |                           | min.  | typ. | max. |               |
| Collector-emitter breakdown voltage  | $V_{(BR)CES}$ | $V_{GE}=0V, I_C=1.5mA$    | 1200  |      |      | V             |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $V_{GE}=15V, I_C=25A$     | 1.8   | 2.2  | 2.6  |               |
| Gate-emitter threshold voltage       | $V_{GE(th)}$  | $I_C=1mA, V_{GE}=V_{CE}$  | 4.5   | 5.5  | 6.5  |               |
| Zero gate voltage collector current  | $I_{CES}$     | $V_{CE}=1200V, V_{GE}=0V$ |       |      | 3.2  | $\mu\text{A}$ |
| Gate-emitter leakage current         | $I_{GES}$     | $V_{CE}=0V, V_{GE}=20V$   |       |      | 120  | nA            |

## ELECTRICAL CHARACTERISTICS (tested at component):

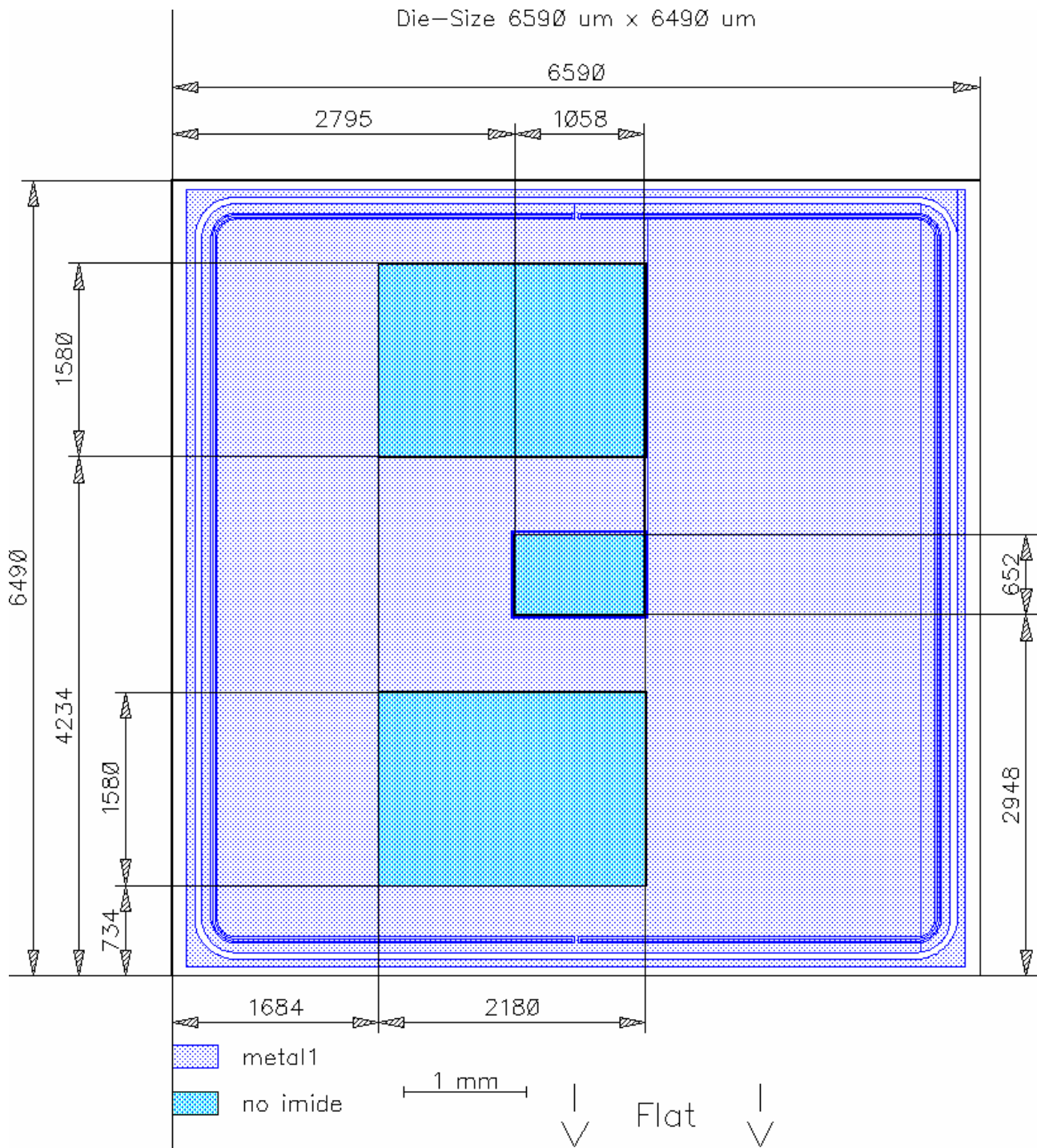
| Parameter                    | Symbol     | Conditions    | Value |      |      | Unit |
|------------------------------|------------|---------------|-------|------|------|------|
|                              |            |               | min.  | typ. | max. |      |
| Input capacitance            | $C_{iss}$  | $V_{CE}=25V,$ | -     | 1.65 | -    | nF   |
| Output capacitance           | $C_{oss}$  | $V_{GE}=0V,$  | -     | -    | -    |      |
| Reverse transfer capacitance | $C_{riss}$ | $f=1MHz$      | -     | 0.11 | -    |      |

## SWITCHING CHARACTERISTICS (tested at component), Inductive Load

| Parameter           | Symbol       | Conditions <sup>1)</sup>            | Value |      |      | Unit |
|---------------------|--------------|-------------------------------------|-------|------|------|------|
|                     |              |                                     | min.  | typ. | max. |      |
| Turn-on delay time  | $t_{d(on)}$  | $T_j=125\text{ °C}$                 | -     | 70   | -    | ns   |
| Rise time           | $t_r$        | $V_{CC}=600V,$                      | -     | 50   | -    |      |
| Turn-off delay time | $t_{d(off)}$ | $I_C=25A,$                          | -     | 320  | -    |      |
| Fall time           | $t_f$        | $V_{GE}=\pm 15V,$<br>$R_G=33\Omega$ | -     | 60   | -    |      |

<sup>1)</sup> values also influenced by parasitic L- and C- in measurement and package.

**CHIP DRAWING:**



**FURTHER ELECTRICAL CHARACTERISTICS:**

|  |                     |                           |
|--|---------------------|---------------------------|
| This chip data sheet refers to the device data sheet | BSM25GD120DLC E3224 | Package Econo 2 short pin |
|--|---------------------|---------------------------|

**DESCRIPTION:**

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

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